



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-11-22
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH8R06D	HTDK*R53S11G	A	SHENZHEN B/E	2016-11-22
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.25-4.5	2	Through-hole	
Comment	DO 220			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	HTDK*RS3511G					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	7.437	mg	supplier	die	Silicon (Si)	7440-21-3		7.307	mg	982520	3846
				supplier	metallization	Aluminium (Al)	7429-90-5		0.064	mg	8606	34
				supplier	Passivation	Silicon Oxide	7631-86-9		0.021	mg	2824	11
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	403	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	941	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.035	mg	4706	18
Leadframe	Copper & its alloys	1185.417	mg	supplier	alloy	Copper (Cu)	7440-50-8		1182.771	mg	997768	622511
				supplier	alloy	Iron (Fe)	7439-89-6		1.184	mg	999	623
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.355	mg	299	187
				supplier	metallization	Nickel (Ni)	7440-02-0		1.107	mg	934	583
Soft solder	Solder	5.175	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.942	mg	954976	2601
				supplier	solder	Silver (Ag)	7440-22-4		0.129	mg	24928	68
				supplier	solder	Tin (Sn)	7440-31-5		0.104	mg	20096	55
Bonding wires	Other inorganic materials	2.463	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.463	mg	1000000	1296
Encapsulation	Other Organic Materials	695.267	mg	supplier	mold compound	Silica, vitreous	60676-86-0		604.882	mg	870000	318359
				supplier	mold compound	Epoxy resin	25068-38-6		69.527	mg	100000	36593
				supplier	mold compound	Phenol resin	29690-82-2		17.382	mg	25000	9148
				supplier	mold compound	Carbon Black	1333-86-4		3.476	mg	5000	1829
Connections coating	Solder	4.241	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.241	mg	1000000	2232